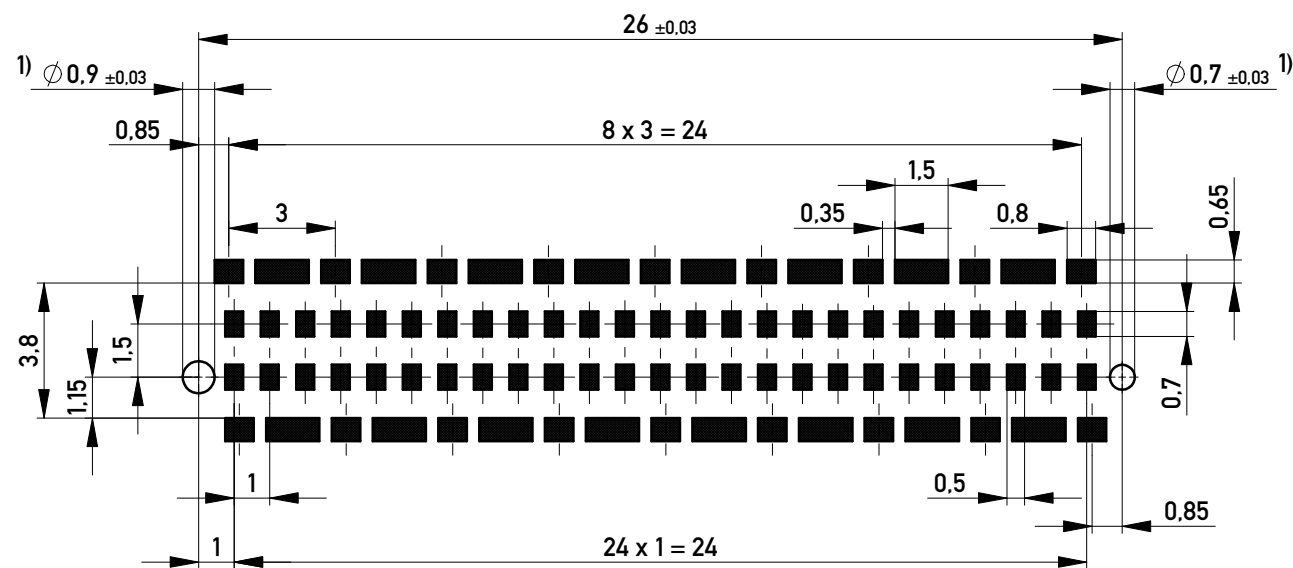
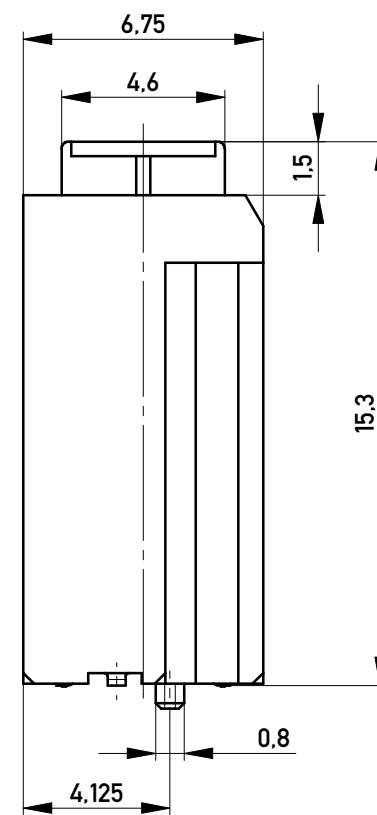


Leiterplatten-Layout Vorschlag / recommended PCB-layout

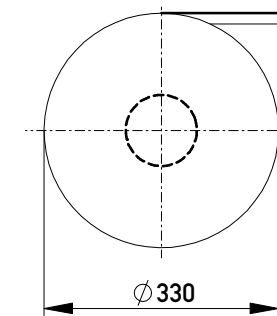


1) Durchmesser des Bohrers / drill tool

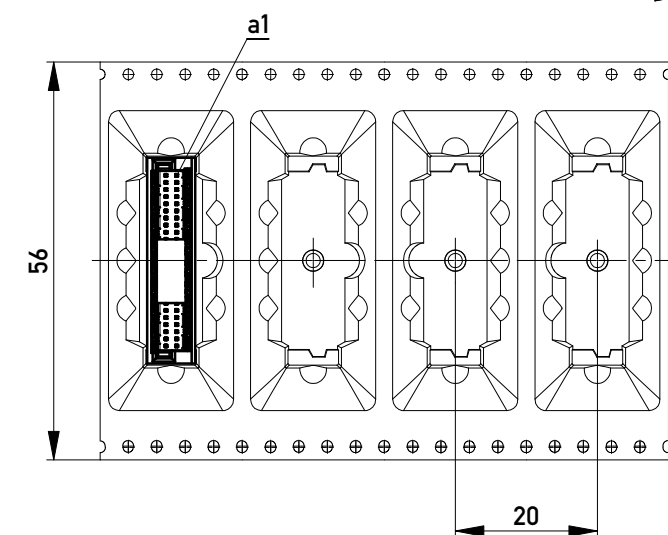
Für weitere Layout Details bitte
 Applikations Schrift MicroSpeed beachten.
 For further layout details please consider
 MicroSpeed application note.



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
 tape on reel packaging according to DIN IEC 60286-3
 Verpackungseinheit: 170 Stück
 packaging unit: 170 pcs



Abspulrichtung - Reel off direction



Anforderungsstufe 1
 performance level 1

Kontaktbereich vergoldet
 mating area gold plating

Anschlussbereich verzinkt 4-6 μm
 terminal area 4-6 μm tin plating

Koplanarität der Anschlüsse $\leq 0,1$ mm
 coplanarity area of termination $\leq 0,1$ mm

| | | | |
|--|--|--------------|--|
| Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using. | Tolerances All Dimensions in mm | Scale | 5:1 |
| | | Designation | M10 SMD BM EMV, 50 polig M10 SMD BM EMV, 50 pin |
| Index | Date | www.ERNI.com | |
| | | 484290 | |
| Class | | MSPEED | |

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